

通信主题专区

Communications Segment



国际通信创新论坛

International Communications Innovation Forum

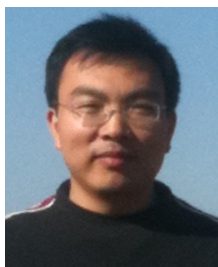
2012年3月22日, W3馆M10会议室(2楼)

March 22, 2012, Conference Room M10 in Hall W3 (on the 2<sup>nd</sup> Floor)

时间   Time	演讲题目   Presentation	演讲嘉宾   Speaker
09:30-10:00	Pervasive ICT: from Antenna to Cloud @ iWireless	华为技术有限公司, 吴建军, 高级经理, 主任工程师 Huawei Technologies Co., Ltd., Jianjun Wu, Program Manager, Corporate Research Department
10:00-10:30	片上基站: 飞思卡尔面向4G Femto/Pico基站的高度集成的解决方案 Basestation on-a-chip: A Highly Integrated Solution From Freescale for 4G Femto/Pico Basestation	飞思卡尔半导体, 曲大健, 无线接入产品部亚太区市场经理 Freescale Semiconductor, Freeman Qu, Marketing Manager, Wireless Access Division, Freescale Asia
10:30-11:00	适用于TD-LTE的TI KeyStone SoC创新架构 TI keystone SoC architecture innovation fit for TD-LTE	德州仪器半导体技术(上海)有限公司, 杨刚, 通信系统架构部门经理 Texas Instruments Semiconductor Technologies (Shanghai) Co., Ltd., George Yang, Manager, CI System Engineering, DSPTS China
11:00-11:30	TD-LTE试验进展 Progress of TD-LTE trial	信息产业部电信研究院通信标准研究所, 林辉, 无线与移动研究部主任工程师 Lin Hui, Manager Engineer, Radio and Mobile Communication Dept., Institute of Communication Standards Research
11:30-12:00	待定 TBA	Broadcom Corporation, Srinivasan Balaji, Product Line Manager, Network Switch Business Unit, Infrastructure and Networking Group
12:00-12:30	Multilayer Organics: A New Paradigm in RF Electronics	AVX Corporation, George White, Business Unit Manager

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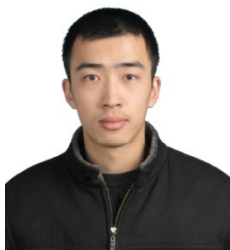


吴建军 | Jianjun Wu  
高级经理, 主任工程师  
Program Manager, Corporate Research Department  
华为技术有限公司 | Huawei Technologies Co., Ltd.



【演讲题目】 Pervasive ICT: from Antenna to Cloud @ iWireless

负责下一代无线通信系统研究工作, 主持国家重大专项。参与3GPP, IEEE相关国际标准的制定。



林辉 博士 | Lin Hui  
无线与移动研究部主任工程师, 信息产业部电信研究院通信标准研究所  
Manager Engineer, Radio and Mobile Communication Dept., Institute of  
Communication Standards Research



【演讲题目】 TD-LTE试验进展  
【Presentation】 Progress of TD-LTE trial

2004年进入工业和信息化部电信研究院工作, 主要从事4G技术的研究和国际标准化工作, 参与了3GPP LTE/LTE-Advanced技术标准和ITU IMT-Advanced国际建议的制定过程。

Hui Lin, Ph.D., has worked in telecom research institute in the Ministry of Industry and Information Technology since 2004. He mainly engaged in 4G technology research and international standardization, moreover, he also participated in the 3GPP LTE/LTE - Advanced technology standards and formulating international recommendations of ITU IMT-Advanced.



杨刚 | George Yang  
通信系统架构部门经理  
Manager, CI System Engineering, DSPS China  
德州仪器半导体技术(上海)有限公司  
Texas instruments Semiconductor Technologies (Shanghai) Co., Ltd.



【演讲题目】 适用于TD-LTE的TI KeyStone SoC创新架构  
【Presentation】 TI keystone SoC architecture innovation fit for TD-LTE

杨刚先生现任德州仪器半导体技术(上海)有限公司通信系统架构部门经理, 主要负责TI高性能多核数字信号处理器(DSP)在中国通信等领域的系统应用和产品需求定义。在2003年加入TI之前, 杨刚先生曾服务于中兴通讯公司, 负责组建DSP开发团队, 以及GSM/GPRS基带子系统的设计、开发、系统集成和调试, 积累了丰富的DSP应用和无线系统经验。杨刚先生于2003年加入TI, 起初主要从事基于TI高性能DSP的3G系统应用工作, 之后担任中国区通信架构应用部门FAE经理, 主要负责TI高性能DSP在中国市场上的应用支持。2011年起, 担任中国区通信系统架构部门经理。

【摘要】 本次演讲深入分析TD-LTE和DSP厂商所面临的挑战, 介绍TI在Keystone Soc的架构创新, 展现TI基于Keystone架构针对TD-LTE的Soc产品和解决方案, 并探讨Keystone Soc架构上的多模解决方案。

【Abstract】 This presentation analyzes the challenges for TD-LTE and the challenges for DSP vendor. And then introduces TI KeyStone SoC Architecture Innovation. TI SoC products & solutions for TD-LTE based on KeyStone Architecture will be demonstrated. Finally, the multi-mode solution on KeyStone SoC Architecture will be discussed.



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**曲大健 | Freeman Qu**  
无线接入产品部亚太区市场经理  
Marketing Manager, Wireless Access Division, Freescale Asia  
飞思卡尔半导体  
Freescale Semiconductor



**【演讲题目】**片上基站：飞思卡尔面向4G Femto/Pico基站的高度集成的解决方案  
**【Presentation】** Basestation on-a-chip: A highly integrated solution from Freescale for 4G Femto/Pico basestation

曲大健先生在无线通信行业拥有超过18年的经验，他在各个跨国公司一直担任研发、技术支持、产品营销以及销售方面的职位。曲先生目前担任飞思卡尔无线接入产品部亚太区市场经理，主要负责亚太区DSP和PQ产品的营销和技术支持。主要的应用范围涵盖3G、4G宏基站、pico/femto基站等无线基带解决方案。曲先生于1993年毕业于清华大学，获得博士学位，主修数字信号处理和模式识别专业。With over 18 years of experiences in wireless communication industry, Freeman Qu holds positions in R&D, Technical support, Product Marketing as well as sales when serving in various multi-national companies. Currently as Marketing Manager in Freescale, Freeman Qu is responsible for marketing and technical support of DSP and PQ products in Asia area. Main application areas cover wireless baseband solutions for 3G, 4G macro base station, pico/femto base station, etc. Freeman Qu graduated from Tsinghua university in 1993 with PhD degree, majored in Digital Signal Processing and Pattern Recognition.

**【摘要】**作为领先的无线解决方案提供商，飞思卡尔向业界推出下一代高度集成、低功耗、高性能且符合多项标准（LTE和UMTS等）的SoC解决方案。该SoC利用备受业界认可的飞思卡尔的PQ和DSP技术，另外还包括许多创新设计。新的产品系列支持4G网络，并推动Femto/Pico基站从概念变为现实。

**【Abstract】** As a key wireless solution provider, Freescale moves to the next generation with a highly integrated, lower power, high performance and multi-standard (LTE, UMTS, etc.) SoC solution to the industry. This SoC leveraged the industry proof PQ and DSP technologies from Freescale, plus many innovative new designs. The new product family enables the 4G network and drive Femto/Pico basestation from concept to reality.

**George White**  
Business Unit Manager  
AVX Corporaton



**【Presentation】** Multilayer Organics: A New Paradigm in RF Electronics

George White is currently the Business Manager for Multilayer Organic RF Products. He holds over 30 US and International patents in microelectronics and has authored numerous publications. He holds a PhD in Metallurgical and Materials Engineering from the University of Illinois.

**【Abstract】** AVX has developed a new line of high Q RF passive components using low loss organic materials. The new technology, termed MultiLayer Organic Components or MLO can support both discrete and integral passive components such as capacitors and inductors, diplexers, couplers, band pass filters and baluns, in typical EIA standard or custom sizes. This new class of RF passive devices represent a paradigm shift from traditional ceramic and silicon based passive components. MLO RF passive components are manufactured using traditional large area printed circuit board technologies and therefore offer the opportunity to realize low cost RF components. The ability to integrate disparate layers in a multilayer fashion also represents the ability to realize custom filters across a wide frequency range.